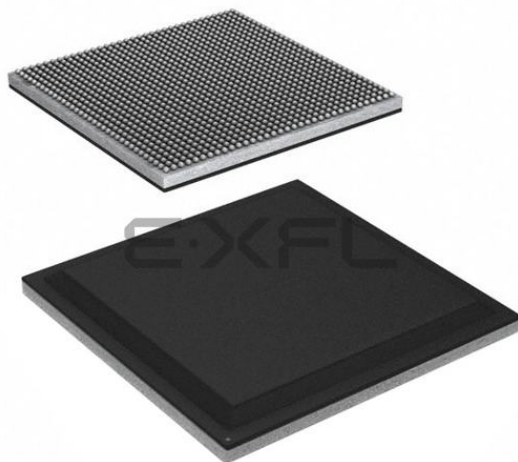




Welcome to [E-XFL.COM](https://www.e-xfl.com)

Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are Embedded - System On Chip (SoC)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions, SoCs combine a central

Details

Product Status	Active
Architecture	MCU, FPGA
Core Processor	Quad ARM® Cortex®-A53 MPCore™ with CoreSight™, Dual ARM®Cortex™-R5 with CoreSight™, ARM Mali™ -400 MP2
Flash Size	-
RAM Size	256KB
Peripherals	DMA, WDT
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	600MHz, 667MHz, 1.5GHz
Primary Attributes	Zynq®UltraScale+™ FPGA, 747K+ Logic Cells
Operating Temperature	0°C ~ 100°C (TJ)
Package / Case	1156-BBGA, FCBGA
Supplier Device Package	1156-FCBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xczu15eg-3ffvb1156e

Recommended Operating Conditions

Table 2: Recommended Operating Conditions⁽¹⁾⁽²⁾

Symbol	Description	Min	Typ	Max	Units
Processor System					
$V_{CC_PSINTFP}^{(3)}$	PS full-power domain supply voltage.	0.808	0.850	0.892	V
	For -1LI and -2LE ($V_{CCINT} = 0.72V$) devices: PS full-power domain supply voltage.	0.808	0.850	0.892	V
	For -3E devices: PS full-power domain supply voltage.	0.873	0.900	0.927	V
$V_{CC_PSINTLP}$	PS low-power domain supply voltage.	0.808	0.850	0.892	V
	For -1LI and -2LE ($V_{CCINT} = 0.72V$) devices: PS low-power domain supply voltage.	0.808	0.850	0.892	V
	For -3E devices: PS low-power domain supply voltage.	0.873	0.900	0.927	V
V_{CC_PSAUX}	PS auxiliary supply voltage.	1.710	1.800	1.890	V
$V_{CC_PSINTFP_DDR}^{(3)}$	PS DDR controller and PHY supply voltage.	0.808	0.850	0.892	V
	For -1LI and -2LE ($V_{CCINT} = 0.72V$) devices: PS DDR controller and PHY supply voltage.	0.808	0.850	0.892	V
	For -3E devices: PS DDR controller and PHY supply voltage.	0.873	0.900	0.927	V
V_{CC_PSADC}	PS SYSMON ADC supply voltage relative to GND_PSADC.	1.710	1.800	1.890	V
V_{CC_PSPLL}	PS PLL supply voltage.	1.164	1.200	1.236	V
$V_{PS_MGTRAVCC}$	PS-GTR supply voltage.	0.825	0.850	0.875	V
$V_{PS_MGTRAVTT}$	PS-GTR termination voltage.	1.746	1.800	1.854	V
$V_{CCO_PSDDR}^{(4)}$	PS DDR I/O supply voltage.	1.06	–	1.575	V
$V_{CC_PSDDR_PLL}$	PS DDR PLL supply voltage.	1.710	1.800	1.890	V
$V_{CCO_PSIO}^{(5)}$	PS I/O supply.	1.710	–	3.465	V
V_{PSIN}	PS I/O input voltage.	–0.200	–	$V_{CCO_PSIO} + 0.200$	V
	PS DDR I/O input voltage.	–0.200	–	$V_{CCO_PSDDR} + 0.200$	
$V_{CC_PSBATT}^{(6)}$	PS battery-backed RAM and battery-backed real-time clock (RTC) supply voltage.	1.200	–	1.500	V
Programmable Logic					
V_{CCINT}	PL internal supply voltage.	0.825	0.850	0.876	V
	For -1LI and -2LE ($V_{CCINT} = 0.72V$) devices: PL internal supply voltage.	0.698	0.720	0.742	V
	For -3E devices: PL internal supply voltage.	0.873	0.900	0.927	V
$V_{CCINT_IO}^{(7)}$	PL internal supply voltage for the I/O banks.	0.825	0.850	0.876	V
	For -1LI and -2LE ($V_{CCINT} = 0.72V$) devices: PL internal supply voltage for the I/O banks.	0.825	0.850	0.876	V
	For -3E devices: PL internal supply voltage for the I/O banks.	0.873	0.900	0.927	V
V_{CCBRAM}	Block RAM supply voltage.	0.825	0.850	0.876	V
	For -3E devices: block RAM supply voltage.	0.873	0.900	0.927	V
V_{CCAUX}	Auxiliary supply voltage.	1.746	1.800	1.854	V

Table 2: Recommended Operating Conditions⁽¹⁾⁽²⁾ (Cont'd)

Symbol	Description	Min	Typ	Max	Units
$V_{CCO}^{(8)}$	Supply voltage for HD I/O banks.	1.140	–	3.400	V
	Supply voltage for HP I/O banks.	0.950	–	1.900	V
$V_{CCAUX_IO}^{(9)}$	Auxiliary I/O supply voltage.	1.746	1.800	1.854	V
$V_{IN}^{(10)}$	I/O input voltage.	–0.200	–	$V_{CCO} + 0.200$	V
$I_{IN}^{(11)}$	Maximum current through any PL or PS pin in a powered or unpowered bank when forward biasing the clamp diode.	–	–	10	mA
GTH or GTY Transceiver					
$V_{MGTAVCC}^{(12)}$	Analog supply voltage for the GTH or GTY transceiver.	0.873	0.900	0.927	V
$V_{MGTAVTT}^{(12)}$	Analog supply voltage for the GTH or GTY transmitter and receiver termination circuits.	1.164	1.200	1.236	V
$V_{MGTVCCAUX}^{(12)}$	Auxiliary analog QPLL voltage supply for the transceivers.	1.746	1.800	1.854	V
$V_{MGTAVTTRCAL}^{(12)}$	Analog supply voltage for the resistor calibration circuit of the GTH or GTY transceiver column.	1.164	1.200	1.236	V
VCU					
V_{CCINT_VCU}	Internal supply voltage for the VCU.	0.825	0.850	0.876	V
	For -1LI and -2LE ($V_{CCINT} = 0.72V$) devices: Internal supply voltage for the VCU.	0.825	0.850	0.876	V
	For -3E devices: Internal supply voltage for the VCU.	0.873	0.900	0.927	V

V_{IN} Maximum Allowed AC Voltage Overshoot and Undershoot

Table 6: V_{IN} Maximum Allowed AC Voltage Overshoot and Undershoot for HD I/O Banks⁽¹⁾

AC Voltage Overshoot	% of UI at -40°C to 100°C	AC Voltage Undershoot	% of UI at -40°C to 100°C
$V_{CCO} + 0.30$	100%	-0.30	100%
$V_{CCO} + 0.35$	100%	-0.35	90%
$V_{CCO} + 0.40$	100%	-0.40	78%
$V_{CCO} + 0.45$	100%	-0.45	40%
$V_{CCO} + 0.50$	100%	-0.50	24%
$V_{CCO} + 0.55$	100%	-0.55	18.0%
$V_{CCO} + 0.60$	100%	-0.60	13.0%
$V_{CCO} + 0.65$	100%	-0.65	10.8%
$V_{CCO} + 0.70$	92%	-0.70	9.0%
$V_{CCO} + 0.75$	92%	-0.75	7.0%
$V_{CCO} + 0.80$	92%	-0.80	6.0%
$V_{CCO} + 0.85$	92%	-0.85	5.0%
$V_{CCO} + 0.90$	92%	-0.90	4.0%
$V_{CCO} + 0.95$	92%	-0.95	2.5%

Notes:

1. A total of 200 mA per bank should not be exceeded.

Table 7: V_{IN} Maximum Allowed AC Voltage Overshoot and Undershoot for HP I/O Banks⁽¹⁾⁽²⁾

AC Voltage Overshoot	% of UI at -40°C to 100°C	AC Voltage Undershoot	% of UI at -40°C to 100°C
$V_{CCO} + 0.30$	100%	-0.30	100%
$V_{CCO} + 0.35$	100%	-0.35	100%
$V_{CCO} + 0.40$	92%	-0.40	92%
$V_{CCO} + 0.45$	50%	-0.45	50%
$V_{CCO} + 0.50$	20%	-0.50	20%
$V_{CCO} + 0.55$	10%	-0.55	10%
$V_{CCO} + 0.60$	6%	-0.60	6%
$V_{CCO} + 0.65$	2%	-0.65	2%
$V_{CCO} + 0.70$	2%	-0.70	2%

Notes:

1. A total of 200 mA per bank should not be exceeded.
2. For UI smaller than 20 μs .

Table 15: SelectIO DC Input and Output Levels for HP I/O Banks⁽¹⁾⁽²⁾⁽³⁾

I/O Standard	V _{IL}		V _{IH}		V _{OL}	V _{OH}	I _{OL}	I _{OH}
	V, Min	V, Max	V, Min	V, Max	V, Max	V, Min	mA	mA
HSTL_I	−0.300	V _{REF} − 0.100	V _{REF} + 0.100	V _{CCO} + 0.300	0.400	V _{CCO} − 0.400	5.8	−5.8
HSTL_I_12	−0.300	V _{REF} − 0.080	V _{REF} + 0.080	V _{CCO} + 0.300	25% V _{CCO}	75% V _{CCO}	4.1	−4.1
HSTL_I_18	−0.300	V _{REF} − 0.100	V _{REF} + 0.100	V _{CCO} + 0.300	0.400	V _{CCO} − 0.400	6.2	−6.2
HSUL_12	−0.300	V _{REF} − 0.130	V _{REF} + 0.130	V _{CCO} + 0.300	20% V _{CCO}	80% V _{CCO}	0.1	−0.1
LVC MOS12	−0.300	35% V _{CCO}	65% V _{CCO}	V _{CCO} + 0.300	0.400	V _{CCO} − 0.400	Note 4	Note 4
LVC MOS15	−0.300	35% V _{CCO}	65% V _{CCO}	V _{CCO} + 0.300	0.450	V _{CCO} − 0.450	Note 5	Note 5
LVC MOS18	−0.300	35% V _{CCO}	65% V _{CCO}	V _{CCO} + 0.300	0.450	V _{CCO} − 0.450	Note 5	Note 5
LVDCI_15	−0.300	35% V _{CCO}	65% V _{CCO}	V _{CCO} + 0.300	0.450	V _{CCO} − 0.450	7.0	−7.0
LVDCI_18	−0.300	35% V _{CCO}	65% V _{CCO}	V _{CCO} + 0.300	0.450	V _{CCO} − 0.450	7.0	−7.0
SSTL12	−0.300	V _{REF} − 0.100	V _{REF} + 0.100	V _{CCO} + 0.300	V _{CCO} /2 − 0.150	V _{CCO} /2 + 0.150	8.0	−8.0
SSTL135	−0.300	V _{REF} − 0.090	V _{REF} + 0.090	V _{CCO} + 0.300	V _{CCO} /2 − 0.150	V _{CCO} /2 + 0.150	9.0	−9.0
SSTL15	−0.300	V _{REF} − 0.100	V _{REF} + 0.100	V _{CCO} + 0.300	V _{CCO} /2 − 0.175	V _{CCO} /2 + 0.175	10.0	−10.0
SSTL18_I	−0.300	V _{REF} − 0.125	V _{REF} + 0.125	V _{CCO} + 0.300	V _{CCO} /2 − 0.470	V _{CCO} /2 + 0.470	7.0	−7.0
MIPI_DPHY_DCI_LP ⁽⁶⁾	−0.300	0.550	0.880	V _{CCO} + 0.300	0.050	1.100	0.01	−0.01

Notes:

1. Tested according to relevant specifications.
2. Standards specified using the default I/O standard configuration. For details, see the *UltraScale Architecture SelectIO Resources User Guide* ([UG571](#)).
3. POD10 and POD12 DC input and output levels are shown in [Table 16](#), [Table 20](#), [Table 21](#), and [Table 22](#).
4. Supported drive strengths of 2, 4, 6, or 8 mA in HP I/O banks.
5. Supported drive strengths of 2, 4, 6, 8, or 12 mA in HP I/O banks.
6. Low-power option for MIPI_DPHY_DCI.

Table 16: DC Input Levels for Single-ended POD10 and POD12 I/O Standards⁽¹⁾⁽²⁾

I/O Standard	V _{IL}		V _{IH}	
	V, Min	V, Max	V, Min	V, Max
POD10	−0.300	V _{REF} − 0.068	V _{REF} + 0.068	V _{CCO} + 0.300
POD12	−0.300	V _{REF} − 0.068	V _{REF} + 0.068	V _{CCO} + 0.300

Notes:

1. Tested according to relevant specifications.
2. Standards specified using the default I/O standard configuration. For details, see the *UltraScale Architecture SelectIO Resources User Guide* ([UG571](#)).

Table 17: Differential SelectIO DC Input and Output Levels

I/O Standard	V _{ICM} (V) ⁽¹⁾			V _{ID} (V) ⁽²⁾			V _{ILHS} ⁽³⁾	V _{IHHS} ⁽³⁾	V _{OCM} (V) ⁽⁴⁾			V _{OD} (V) ⁽⁵⁾		
	Min	Typ	Max	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max
SUB_LVDS ⁽⁸⁾	0.500	0.900	1.300	0.070	–	–	–	–	0.700	0.900	1.100	0.100	0.150	0.200
LVPECL	0.300	1.200	1.425	0.100	0.350	0.600	–	–	–	–	–	–	–	–
SLVS_400_18	0.070	0.200	0.330	0.140	–	0.450	–	–	–	–	–	–	–	–
SLVS_400_25	0.070	0.200	0.330	0.140	–	0.450	–	–	–	–	–	–	–	–
MIPI_DPHY_DCI_HS ⁽⁹⁾	0.070	–	0.330	0.070	–	–	–0.040	0.460	0.150	0.200	0.250	0.140	0.200	0.270

Notes:

- V_{ICM} is the input common mode voltage.
- V_{ID} is the input differential voltage (Q – $\bar{Q}$).
- V_{IHHS} and V_{ILHS} are the single-ended input high and low voltages, respectively.
- V_{OCM} is the output common mode voltage.
- V_{OD} is the output differential voltage (Q – $\bar{Q}$).
- LVDS_25 is specified in Table 23.
- LVDS is specified in Table 24.
- Only the SUB_LVDS receiver is supported in HD I/O banks.
- High-speed option for MIPI_DPHY_DCI. The V_{ID} maximum is aligned with the standard's specification. A higher V_{ID} is acceptable as long as the V_{IN} specification is also met.

Table 18: Complementary Differential SelectIO DC Input and Output Levels for HD I/O Banks

I/O Standard	V _{ICM} (V) ⁽¹⁾			V _{ID} (V) ⁽²⁾		V _{OL} (V) ⁽³⁾	V _{OH} (V) ⁽⁴⁾	I _{OL}	I _{OH}
	Min	Typ	Max	Min	Max	Max	Min	mA	mA
DIFF_HSTL_I	0.300	0.750	1.125	0.100	–	0.400	V _{CCO} – 0.400	8.0	–8.0
DIFF_HSTL_I_18	0.300	0.900	1.425	0.100	–	0.400	V _{CCO} – 0.400	8.0	–8.0
DIFF_HSUL_12	0.300	0.600	0.850	0.100	–	20% V _{CCO}	80% V _{CCO}	0.1	–0.1
DIFF_SSTL12	0.300	0.600	0.850	0.100	–	(V _{CCO} /2) – 0.150	(V _{CCO} /2) + 0.150	14.25	–14.25
DIFF_SSTL135	0.300	0.675	1.000	0.100	–	(V _{CCO} /2) – 0.150	(V _{CCO} /2) + 0.150	8.9	–8.9
DIFF_SSTL135_II	0.300	0.675	1.000	0.100	–	(V _{CCO} /2) – 0.150	(V _{CCO} /2) + 0.150	13.0	–13.0
DIFF_SSTL15	0.300	0.750	1.125	0.100	–	(V _{CCO} /2) – 0.175	(V _{CCO} /2) + 0.175	8.9	–8.9
DIFF_SSTL15_II	0.300	0.750	1.125	0.100	–	(V _{CCO} /2) – 0.175	(V _{CCO} /2) + 0.175	13.0	–13.0
DIFF_SSTL18_I	0.300	0.900	1.425	0.100	–	(V _{CCO} /2) – 0.470	(V _{CCO} /2) + 0.470	8.0	–8.0
DIFF_SSTL18_II	0.300	0.900	1.425	0.100	–	(V _{CCO} /2) – 0.600	(V _{CCO} /2) + 0.600	13.4	–13.4

Notes:

- V_{ICM} is the input common mode voltage.
- V_{ID} is the input differential voltage.
- V_{OL} is the single-ended low-output voltage.
- V_{OH} is the single-ended high-output voltage.

LVDS DC Specifications (LVDS_25)

The LVDS_25 standard is available in the HD I/O banks. See the *UltraScale Architecture SelectIO Resources User Guide* ([UG571](#)) for more information.

Table 23: LVDS_25 DC Specifications

Symbol	DC Parameter	Min	Typ	Max	Units
$V_{CCO}^{(1)}$	Supply voltage.	2.375	2.500	2.625	V
V_{IDIFF}	Differential input voltage: ($Q - \bar{Q}$), $Q = \text{High}$ ($\bar{Q} - Q$), $\bar{Q} = \text{High}$	100	350	600 ⁽²⁾	mV
V_{ICM}	Input common-mode voltage.	0.300	1.200	1.425	V

Notes:

1. LVDS_25 in HD I/O banks supports inputs only. LVDS_25 inputs without internal termination have no V_{CCO} requirements. Any V_{CCO} can be chosen as long as the input voltage levels do not violate the *Recommended Operating Condition* (Table 2) specification for the V_{IN} I/O pin voltage.
2. Maximum V_{IDIFF} value is specified for the maximum V_{ICM} specification. With a lower V_{ICM} , a higher V_{IDIFF} is tolerated only when the recommended operating conditions and overshoot/undershoot V_{IN} specifications are maintained.

LVDS DC Specifications (LVDS)

The LVDS standard is available in the HP I/O banks. See the *UltraScale Architecture SelectIO Resources User Guide* ([UG571](#)) for more information.

Table 24: LVDS DC Specifications

Symbol	DC Parameter	Conditions	Min	Typ	Max	Units
$V_{CCO}^{(1)}$	Supply voltage.		1.710	1.800	1.890	V
$V_{ODIFF}^{(2)}$	Differential output voltage: ($Q - \bar{Q}$), $Q = \text{High}$ ($\bar{Q} - Q$), $\bar{Q} = \text{High}$	$R_T = 100\Omega$ across Q and $\bar{Q}$ signals	247	350	454	mV
$V_{OCM}^{(2)}$	Output common-mode voltage.	$R_T = 100\Omega$ across Q and $\bar{Q}$ signals	1.000	1.250	1.425	V
$V_{IDIFF}^{(3)}$	Differential input voltage: ($Q - \bar{Q}$), $Q = \text{High}$ ($\bar{Q} - Q$), $\bar{Q} = \text{High}$		100	350	600 ⁽³⁾	mV
$V_{ICM_DC}^{(4)}$	Input common-mode voltage (DC coupling).		0.300	1.200	1.425	V
$V_{ICM_AC}^{(5)}$	Input common-mode voltage (AC coupling).		0.600	–	1.100	V

Notes:

1. In HP I/O banks, when LVDS is used with input-only functionality, it can be placed in a bank where the V_{CCO} levels are different from the specified level only if internal differential termination is not used. In this scenario, V_{CCO} must be chosen to ensure the input pin voltage levels do not violate the *Recommended Operating Condition* (Table 2) specification for the V_{IN} I/O pin voltage.
2. V_{OCM} and V_{ODIFF} values are for LVDS_PRE_EMPHASIS = FALSE.
3. Maximum V_{IDIFF} value is specified for the maximum V_{ICM} specification. With a lower V_{ICM} , a higher V_{IDIFF} is tolerated only when the recommended operating conditions and overshoot/undershoot V_{IN} specifications are maintained.
4. Input common mode voltage for DC coupled configurations. EQUALIZATION = EQ_NONE (Default).
5. External input common mode voltage specification for AC coupled configurations. EQUALIZATION = EQ_LEVEL0, EQ_LEVEL1, EQ_LEVEL2, EQ_LEVEL3, EQ_LEVEL4.

Table 26: Speed Grade Designations by Device (Cont'd)

Device	Speed Grade, Temperature Ranges, and V_{CCINT} Operating Voltages		
	Advance	Preliminary	Production
XCZU11EG	-3E ($V_{CCINT} = 0.90V$), -2E ($V_{CCINT} = 0.85V$) -2I ($V_{CCINT} = 0.85V$), -2LE ($V_{CCINT} = 0.85V$) -1E ($V_{CCINT} = 0.85V$), -1I ($V_{CCINT} = 0.85V$) -1LI ($V_{CCINT} = 0.85V$) -2LE ($V_{CCINT} = 0.72V$), -1LI ($V_{CCINT} = 0.72V$)		
XCZU15EG	-3E ($V_{CCINT} = 0.90V$), -2E ($V_{CCINT} = 0.85V$) -2I ($V_{CCINT} = 0.85V$), -2LE ($V_{CCINT} = 0.85V$) -1E ($V_{CCINT} = 0.85V$), -1I ($V_{CCINT} = 0.85V$) -1LI ($V_{CCINT} = 0.85V$) -2LE ($V_{CCINT} = 0.72V$), -1LI ($V_{CCINT} = 0.72V$)		
XCZU17EG	-3E ($V_{CCINT} = 0.90V$), -2E ($V_{CCINT} = 0.85V$) -2I ($V_{CCINT} = 0.85V$), -2LE ($V_{CCINT} = 0.85V$) -1E ($V_{CCINT} = 0.85V$), -1I ($V_{CCINT} = 0.85V$) -1LI ($V_{CCINT} = 0.85V$) -2LE ($V_{CCINT} = 0.72V$), -1LI ($V_{CCINT} = 0.72V$)		
XCZU19EG	-3E ($V_{CCINT} = 0.90V$), -2E ($V_{CCINT} = 0.85V$) -2I ($V_{CCINT} = 0.85V$), -2LE ($V_{CCINT} = 0.85V$) -1E ($V_{CCINT} = 0.85V$), -1I ($V_{CCINT} = 0.85V$) -1LI ($V_{CCINT} = 0.85V$) -2LE ($V_{CCINT} = 0.72V$), -1LI ($V_{CCINT} = 0.72V$)		

Notes:

1. The lowest power -1L and -2L devices, where $V_{CCINT} = 0.72V$, are listed in the Vivado Design Suite as -1LV and -2LV respectively.

Table 37: PS Reset Assertion Timing Requirements

Symbol	Description	Min	Typ	Max	Units
T _{PSPOR}	Required PS_POR_B assertion time. ⁽¹⁾	10	–	–	μs
T _{PSRST}	Required PS_SRST_B assertion time.	3	–	–	PS_REF_CLK Clock Cycles

Notes:

1. PS_POR_B must be asserted Low at power-up and continue to be asserted for a duration of T_{PSPOR} after all the PS supply voltages reach minimum levels. PS_POR_B must be asserted Low for the duration of T_{POR} when the PS and PL power-up at the same time and the application uses both the PS and PL after power-up.

Table 38: PS Clocks Switching Characteristics

Symbol	Description	Speed Grade			Units
		-3	-2	-1	
F _{TOPSW_MAINMAX}	TOPSW_MAIN maximum frequency.	600	533	533	MHz
F _{TOPSW_LSBUSMAX}	TOPSW_LSBUS maximum frequency.	100	100	100	MHz
F _{GDMAMAX}	FPD-DMA maximum frequency.	600	600	600	MHz
F _{DPDMAMAX}	DisplayPort DMA maximum frequency.	600	600	600	MHz
F _{LPD_SWITCH_CTRLMAX}	LPD_SWITCH_CTRL maximum frequency.	600	500	500	MHz
F _{LPD_LSBUS_CTRLMAX}	LPD_LSBUS_CTRL maximum frequency.	100	100	100	MHz
F _{ADMAMAX}	LPD-DMA maximum frequency.	600	500	500	MHz
F _{APLL_TO_LPDMAX}	APLL_TO_LPD maximum frequency.	533	533	533	MHz
F _{DPDLL_TO_LPDMAX}	DPDLL_TO_LPD maximum frequency.	533	533	533	MHz
F _{VPDLL_TO_LPDMAX}	VPDLL_TO_LPD maximum frequency.	533	533	533	MHz
F _{IOPLL_TO_LPDMAX}	IOPLL_TO_LPD maximum frequency.	533	533	533	MHz
F _{RPLL_TO_FPDMAX}	RPLL_TO_FPD maximum frequency.	533	533	533	MHz

PS Configuration

Table 39: Processor Configuration Access Port Switching Characteristics

Symbol	Description	Speed Grade and V _{CCINT} Operating Voltages					Units
		0.90V	0.85V		0.72V		
		-3	-2	-1	-2	-1	
F _{PCAPCK}	Maximum processor configuration access port (PCAP) frequency.	200	200	200	150	150	MHz

Table 40: Boundary-Scan Port Switching Characteristics

Symbol	Description	Speed Grade and V _{CCINT} Operating Voltages					Units
		0.90V	0.85V		0.72V		
		-3	-2	-1	-2	-1	
F _{TCK}	JTAG clock maximum frequency.	25	25	25	15	15	MHz
T _{TAPTCK} /T _{TCKTAP}	TMS and TDI setup and hold.	4.0/2.0	4.0/2.0	4.0/2.0	5.0/2.0	5.0/2.0	ns, Min
T _{TCKTDO}	TCK falling edge to TDO output.	16.1	16.1	16.1	24	24	ns, Max

Notes:

1. The test conditions are configured to the LVCMOS 3.3V I/O standard with a 12 mA drive strength.

PS Interface Specifications

PS Quad-SPI Controller Interface

Table 41: Generic Quad-SPI Interface⁽¹⁾

Symbol	Description	Load Conditions ⁽²⁾	Min	Max	Units
Quad-SPI device clock frequency operating at 150 MHz. Loopback enabled. LVCMOS 1.8V I/O standard.					
T _{DCQSPICLK1}	Quad-SPI clock duty cycle.	15 pF	45	55	%
T _{QSPISSSCLK1}	Slave select asserted to next clock edge.	15 pF	5.0	–	ns
T _{QSPISCLKSS1}	Clock edge to slave select deasserted.	15 pF	5.0	–	ns
T _{QSPICKO1}	Clock to output delay, all outputs.	15 pF	2.9	4.5	ns
T _{QSPIDCK1}	Setup time, all inputs.	15 pF	0.9	–	ns
T _{QSPICKD1}	Hold time, all inputs.	15 pF	1.0	–	ns
F _{QSPICLK1}	Quad-SPI device clock frequency.	15 pF	–	150	MHz
F _{QSPIREFCLK1}	Quad-SPI reference clock frequency.	15 pF	–	300	MHz
Quad-SPI device clock frequency operating at 100 MHz. Loopback enabled. LVCMOS 1.8V I/O standard.					
T _{DCQSPICLK2}	Quad-SPI clock duty cycle.	15 pF	45	55	%
		30 pF	45	55	%
T _{QSPISSSCLK2}	Slave select asserted to next clock edge.	15 pF	5.0	–	ns
		30 pF	5.0	–	ns
T _{QSPISCLKSS2}	Clock edge to slave select deasserted.	15 pF	5.0	–	ns
		30 pF	5.0	–	ns
T _{QSPICKO2}	Clock to output delay, all outputs.	15 pF	3.2	7.4	ns
		30 pF	3.2	7.4	ns
T _{QSPIDCK2}	Setup time, all inputs.	15 pF	2.3	–	ns
		30 pF	2.3	–	ns
T _{QSPICKD2}	Hold time, all inputs.	15 pF	0.0	–	ns
		30 pF	0.0	–	ns
F _{QSPICLK2}	Quad-SPI device clock frequency.	15 pF	–	100	MHz
		30 pF	–	100	MHz
F _{QSPIREFCLK2}	Quad-SPI reference clock frequency.	15 pF	–	200	MHz
		30 pF	–	200	MHz

Notes:

1. The test conditions are configured for the generic Quad-SPI interface at 150/100 MHz with a 12 mA drive strength and fast slew rate.
2. 30 pF loads are for dual-parallel stacked or stacked modes.

PS eMMC Standard Interface

Table 46: eMMC Standard Interface⁽¹⁾

Symbol	Description	Min	Max	Units
eMMC Standard Interface				
T _{DCEMMCHSCLK}	eMMC clock duty cycle.	45	55	%
T _{EMMCHSCKO}	Clock to output delay, all outputs.	–2.0	4.5	ns
T _{EMMCHSDCK}	Input setup time, all inputs.	2.0	–	ns
T _{EMMCHSCKD}	Input hold time, all inputs.	2.0	–	ns
F _{EMMCHSCLK}	eMMC clock frequency.	–	25	MHz
eMMC High-Speed SDR Interface				
T _{DCEMMCHSCLK}	eMMC high-speed SDR clock duty cycle.	45	55	%
T _{EMMCHSCKO}	Clock to output delay, all outputs. ⁽²⁾	3.2	16.8	ns
T _{EMMCHSDIVW}	Input valid data window. ⁽³⁾	0.4	–	UI
F _{EMMCHSCLK}	eMMC high speed SDR clock frequency.	–	50	MHz
eMMC High-Speed DDR Interface				
T _{DCEMMCDDRCLK}	eMMC high-speed DDR clock duty cycle.	45	55	%
T _{EMMCDDRCKO1}	Data clock to output delay. ⁽²⁾	2.7	7.3	ns
T _{EMMCSDR1VW}	Input valid data window. ⁽³⁾	3.5	–	ns
T _{EMMCDDRCKO2}	Command clock to output delay.	3.2	16	ns
T _{EMMCDDRCK2}	Command input setup time.	3.9	–	ns
T _{EMMCDDRCKD2}	Command input hold time.	2.5	–	ns
F _{EMMCDDRCLK}	eMMC high-speed DDR clock frequency.	–	50	MHz
eMMC HS200 Interface				
T _{DCEMMCHS200CLK}	eMMC HS200 clock duty cycle.	40	60	%
T _{EMMCHS200CKO}	Clock to output delay, all outputs. ⁽²⁾	1.0	3.4	ns
T _{EMMCSDR1VW}	Input valid data window. ⁽³⁾	0.4	–	UI
F _{EMMCHS200CLK}	eMMC HS200 clock frequency.	–	200	MHz

Notes:

1. The test conditions for eMMC standard mode use an 8 mA drive strength, fast slew rate, and a 30 pF load. For eMMC high-speed mode, the test conditions use a 12 mA drive strength, fast slew rate, and a 30 pF load. For other eMMC modes, the test conditions use a 12 mA drive strength, fast slew rate, and a 15 pF load.
2. This specification is achieved using pre-determined DLL tuning.
3. This specification is required for capturing input data using DLL tuning.

Table 72: MIPI D-PHY Performance

Description	I/O Bank Type	Speed Grade and V _{CCINT} Operating Voltages					Units
		0.90V	0.85V		0.72V		
		-3(1)	-2(1)	-1	-2	-1	
MIPI D-PHY transmitter or receiver.	HP	1500	1500	1260	1260	1260	Mb/s

Notes:

1. In the SBVA484 package, the data rate is 1260 Mb/s.

Table 73: LVDS Native-Mode 1000BASE-X Support⁽¹⁾

Description	I/O Bank Type	Speed Grade and V _{CCINT} Operating Voltages				
		0.90V	0.85V		0.72V	
		-3	-2	-1	-2	-1
1000BASE-X	HP	Yes				

Notes:

1. 1000BASE-X support is based on the *IEEE Standard for CSMA/CD Access Method and Physical Layer Specifications* (IEEE Std 802.3-2008).

Table 74 provides the maximum data rates for applicable memory standards using the Zynq UltraScale+ MPSoC memory PHY. Refer to [Memory Interfaces](#) for the complete list of memory interface standards supported and detailed specifications. The final performance of the memory interface is determined through a complete design implemented in the Vivado Design Suite, following guidelines in the *UltraScale Architecture PCB Design Guide* ([UG583](#)), electrical analysis, and characterization of the system.

Table 74: Maximum Physical Interface (PHY) Rate for Memory Interfaces

Memory Standard	Package ⁽¹⁾	DRAM Type	Speed Grade and V _{CCINT} Operating Voltages					Units
			0.90V	0.85V		0.72V		
			-3	-2	-1	-2	-1	
DDR4	All FFV packages and FBVB900	Single rank component	2666	2666	2400	2400	2133	Mb/s
		1 rank DIMM ⁽²⁾⁽³⁾⁽⁴⁾	2400	2400	2133	2133	1866	Mb/s
		2 rank DIMM ⁽²⁾⁽⁵⁾	2133	2133	1866	1866	1600	Mb/s
		4 rank DIMM ⁽²⁾⁽⁶⁾	1600	1600	1333	1333	N/A	Mb/s
	SFVC784	Single rank component	2400	2400	2133	2133	1866	Mb/s
		1 rank DIMM ⁽²⁾⁽³⁾	2133	2133	1866	1866	1600	Mb/s
		2 rank DIMM ⁽²⁾⁽⁵⁾	1866	1866	1600	1600	1600	Mb/s
DDR3	All FFV packages and FBVB900	Single rank component	2133	2133	2133	2133	1866	Mb/s
		1 rank DIMM ⁽²⁾⁽³⁾	1866	1866	1866	1866	1600	Mb/s
		2 rank DIMM ⁽²⁾⁽⁵⁾	1600	1600	1600	1600	1333	Mb/s
		4 rank DIMM ⁽²⁾⁽⁶⁾	1066	1066	1066	1066	800	Mb/s
	SFVC784	Single rank component	1866	1866	1866	1866	1600	Mb/s
		1 rank DIMM ⁽²⁾⁽³⁾	1600	1600	1600	1600	1600	Mb/s
		2 rank DIMM ⁽²⁾⁽⁵⁾	1600	1600	1600	1600	1333	Mb/s
		4 rank DIMM ⁽²⁾⁽⁶⁾	1066	1066	1066	1066	800	Mb/s

IOB High Performance (HP) Switching Characteristics

Table 76: IOB High Performance (HP) Switching Characteristics

I/O Standards	T _{INBUF_DELAY_PAD_I}					T _{OUTBUF_DELAY_O_PAD}					T _{OUTBUF_DELAY_TD_PAD}					Units
	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	0.90V		0.85V		0.72V	
	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	-3	-2	-1	-2	-1	
DIFF_HSTL_I_12_F	0.394	0.394	0.402	0.394	0.402	0.423	0.423	0.443	0.423	0.443	0.553	0.553	0.582	0.553	0.582	ns
DIFF_HSTL_I_12_M	0.394	0.394	0.402	0.394	0.402	0.552	0.552	0.583	0.552	0.583	0.641	0.641	0.679	0.641	0.679	ns
DIFF_HSTL_I_12_S	0.394	0.394	0.402	0.394	0.402	0.752	0.752	0.800	0.752	0.800	0.813	0.813	0.868	0.813	0.868	ns
DIFF_HSTL_I_18_F	0.319	0.319	0.339	0.319	0.339	0.456	0.456	0.474	0.456	0.474	0.576	0.576	0.606	0.576	0.606	ns
DIFF_HSTL_I_18_M	0.319	0.319	0.339	0.319	0.339	0.570	0.570	0.603	0.570	0.603	0.653	0.653	0.692	0.653	0.692	ns
DIFF_HSTL_I_18_S	0.319	0.319	0.339	0.319	0.339	0.782	0.782	0.834	0.782	0.834	0.816	0.816	0.871	0.816	0.871	ns
DIFF_HSTL_I_DCI_12_F	0.394	0.394	0.402	0.394	0.402	0.406	0.406	0.429	0.406	0.429	0.534	0.534	0.564	0.534	0.564	ns
DIFF_HSTL_I_DCI_12_M	0.394	0.394	0.402	0.394	0.402	0.557	0.557	0.587	0.557	0.587	0.653	0.653	0.694	0.653	0.694	ns
DIFF_HSTL_I_DCI_12_S	0.394	0.394	0.402	0.394	0.402	0.755	0.755	0.806	0.755	0.806	0.842	0.842	0.907	0.842	0.907	ns
DIFF_HSTL_I_DCI_18_F	0.323	0.323	0.339	0.323	0.339	0.445	0.445	0.461	0.445	0.461	0.566	0.566	0.595	0.566	0.595	ns
DIFF_HSTL_I_DCI_18_M	0.323	0.323	0.339	0.323	0.339	0.555	0.555	0.586	0.555	0.586	0.643	0.643	0.684	0.643	0.684	ns
DIFF_HSTL_I_DCI_18_S	0.323	0.323	0.339	0.323	0.339	0.762	0.762	0.818	0.762	0.818	0.836	0.836	0.900	0.836	0.900	ns
DIFF_HSTL_I_DCI_F	0.397	0.397	0.417	0.397	0.417	0.431	0.431	0.445	0.431	0.445	0.555	0.555	0.575	0.555	0.575	ns
DIFF_HSTL_I_DCI_M	0.397	0.397	0.417	0.397	0.417	0.553	0.553	0.583	0.553	0.583	0.644	0.644	0.684	0.644	0.684	ns
DIFF_HSTL_I_DCI_S	0.397	0.397	0.417	0.397	0.417	0.767	0.767	0.823	0.767	0.823	0.848	0.848	0.912	0.848	0.912	ns
DIFF_HSTL_I_F	0.404	0.404	0.417	0.404	0.417	0.423	0.423	0.443	0.423	0.443	0.549	0.549	0.581	0.549	0.581	ns
DIFF_HSTL_I_M	0.404	0.404	0.417	0.404	0.417	0.555	0.555	0.586	0.555	0.586	0.640	0.640	0.677	0.640	0.677	ns
DIFF_HSTL_I_S	0.404	0.404	0.417	0.404	0.417	0.767	0.767	0.818	0.767	0.818	0.811	0.811	0.866	0.811	0.866	ns
DIFF_HSUL_12_DCI_F	0.381	0.381	0.400	0.381	0.400	0.425	0.425	0.443	0.425	0.443	0.558	0.558	0.586	0.558	0.586	ns
DIFF_HSUL_12_DCI_M	0.381	0.381	0.400	0.381	0.400	0.557	0.557	0.587	0.557	0.587	0.653	0.653	0.694	0.653	0.694	ns
DIFF_HSUL_12_DCI_S	0.381	0.381	0.400	0.381	0.400	0.737	0.737	0.787	0.737	0.787	0.822	0.822	0.885	0.822	0.885	ns
DIFF_HSUL_12_F	0.394	0.394	0.402	0.394	0.402	0.412	0.412	0.430	0.412	0.430	0.538	0.538	0.566	0.538	0.566	ns
DIFF_HSUL_12_M	0.394	0.394	0.402	0.394	0.402	0.552	0.552	0.583	0.552	0.583	0.641	0.641	0.679	0.641	0.679	ns
DIFF_HSUL_12_S	0.394	0.394	0.402	0.394	0.402	0.752	0.752	0.800	0.752	0.800	0.813	0.813	0.868	0.813	0.868	ns
DIFF_POD10_DCI_F	0.411	0.411	0.430	0.411	0.430	0.425	0.425	0.444	0.425	0.444	0.555	0.555	0.584	0.555	0.584	ns
DIFF_POD10_DCI_M	0.411	0.411	0.430	0.411	0.430	0.542	0.542	0.571	0.542	0.571	0.640	0.640	0.681	0.640	0.681	ns
DIFF_POD10_DCI_S	0.411	0.411	0.430	0.411	0.430	0.754	0.754	0.815	0.754	0.815	0.850	0.850	0.917	0.850	0.917	ns
DIFF_POD10_F	0.411	0.411	0.433	0.411	0.433	0.438	0.438	0.459	0.438	0.459	0.569	0.569	0.601	0.569	0.601	ns
DIFF_POD10_M	0.411	0.411	0.433	0.411	0.433	0.538	0.538	0.568	0.538	0.568	0.630	0.630	0.667	0.630	0.667	ns
DIFF_POD10_S	0.411	0.411	0.433	0.411	0.433	0.766	0.766	0.821	0.766	0.821	0.836	0.836	0.894	0.836	0.894	ns
DIFF_POD12_DCI_F	0.407	0.407	0.432	0.407	0.432	0.425	0.425	0.443	0.425	0.443	0.558	0.558	0.586	0.558	0.586	ns
DIFF_POD12_DCI_M	0.407	0.407	0.432	0.407	0.432	0.543	0.543	0.572	0.543	0.572	0.638	0.638	0.678	0.638	0.678	ns
DIFF_POD12_DCI_S	0.407	0.407	0.432	0.407	0.432	0.772	0.772	0.822	0.772	0.822	0.862	0.862	0.929	0.862	0.929	ns
DIFF_POD12_F	0.409	0.409	0.430	0.409	0.430	0.455	0.455	0.476	0.455	0.476	0.595	0.595	0.626	0.595	0.626	ns
DIFF_POD12_M	0.409	0.409	0.430	0.409	0.430	0.551	0.551	0.582	0.551	0.582	0.641	0.641	0.679	0.641	0.679	ns
DIFF_POD12_S	0.409	0.409	0.430	0.409	0.430	0.767	0.767	0.817	0.767	0.817	0.832	0.832	0.889	0.832	0.889	ns
DIFF_SSTL12_DCI_F	0.381	0.381	0.400	0.381	0.400	0.425	0.425	0.443	0.425	0.443	0.558	0.558	0.586	0.558	0.586	ns
DIFF_SSTL12_DCI_M	0.381	0.381	0.400	0.381	0.400	0.557	0.557	0.587	0.557	0.587	0.654	0.654	0.694	0.654	0.694	ns
DIFF_SSTL12_DCI_S	0.381	0.381	0.400	0.381	0.400	0.754	0.754	0.803	0.754	0.803	0.842	0.842	0.908	0.842	0.908	ns

MMCM Switching Characteristics

Table 85: MMCM Specification

Symbol	Description	Speed Grade and V _{CCINT} Operating Voltages					Units
		0.90V	0.85V		0.72V		
		-3	-2	-1	-2	-1	
MMCM_F _{INMAX}	Maximum input clock frequency.	1066	933	800	933	800	MHz
MMCM_F _{INMIN}	Minimum input clock frequency.	10	10	10	10	10	MHz
MMCM_F _{INJITTER}	Maximum input clock period jitter.	< 20% of clock input period or 1 ns Max					
MMCM_F _{INDUTY}	Input duty cycle range: 10–49 MHz.	25–75					%
	Input duty cycle range: 50–199 MHz.	30–70					%
	Input duty cycle range: 200–399 MHz.	35–65					%
	Input duty cycle range: 400–499 MHz.	40–60					%
	Input duty cycle range: >500 MHz.	45–55					%
MMCM_F _{MIN_PSCLK}	Minimum dynamic phase shift clock frequency.	0.01	0.01	0.01	0.01	0.01	MHz
MMCM_F _{MAX_PSCLK}	Maximum dynamic phase shift clock frequency.	550	500	450	500	450	MHz
MMCM_F _{VCOMIN}	Minimum MMCM VCO frequency.	800	800	800	800	800	MHz
MMCM_F _{VCOMAX}	Maximum MMCM VCO frequency.	1600	1600	1600	1600	1600	MHz
MMCM_F _{BANDWIDTH}	Low MMCM bandwidth at typical. ⁽¹⁾	1.00	1.00	1.00	1.00	1.00	MHz
	High MMCM bandwidth at typical. ⁽¹⁾	4.00	4.00	4.00	4.00	4.00	MHz
MMCM_T _{STATPHAOFFSET}	Static phase offset of the MMCM outputs. ⁽²⁾	0.12	0.12	0.12	0.12	0.12	ns
MMCM_T _{OUTJITTER}	MMCM output jitter.	Note 3					
MMCM_T _{OUTDUTY}	MMCM output clock duty cycle precision. ⁽⁴⁾	0.165	0.20	0.20	0.20	0.20	ns
MMCM_T _{LOCKMAX}	MMCM maximum lock time for MMCM_F _{PFDMIN} .	100	100	100	100	100	μs
MMCM_F _{OUTMAX}	MMCM maximum output frequency.	891	775	667	725	667	MHz
MMCM_F _{OUTMIN}	MMCM minimum output frequency. ⁽⁴⁾⁽⁵⁾	6.25	6.25	6.25	6.25	6.25	MHz
MMCM_T _{EXTFDVAR}	External clock feedback variation.	< 20% of clock input period or 1 ns Max					
MMCM_RST _{MINPULSE}	Minimum reset pulse width.	5.00	5.00	5.00	5.00	5.00	ns
MMCM_F _{PFDMAX}	Maximum frequency at the phase frequency detector.	550	500	450	500	450	MHz
MMCM_F _{PFDMIN}	Minimum frequency at the phase frequency detector.	10	10	10	10	10	MHz
MMCM_T _{FBDELAY}	Maximum delay in the feedback path.	5 ns Max or one clock cycle					

Table 88: Global Clock Input to Output Delay Without MMCM (Far Clock Region)

Symbol	Description	Device	Speed Grade and V _{CCINT} Operating Voltages					Units
			0.90V	0.85V		0.72V		
			-3	-2	-1	-2	-1	
SSTL15 Global Clock Input to Output Delay using Output Flip-Flop, Fast Slew Rate, <i>without</i> MMCM.								
T _{ICKOF_FAR}	Global clock input and output flip-flop <i>without</i> MMCM (far clock region).	XCZU2	N/A	5.27	5.68	5.80	6.13	ns
		XCZU3	N/A	5.27	5.68	5.80	6.13	ns
		XCZU4	5.07	6.06	6.61	6.23	7.10	ns
		XCZU5	5.07	6.06	6.61	6.23	7.10	ns
		XCZU6	5.38	6.49	6.97	7.14	7.59	ns
		XCZU7	5.39	6.54	7.01	7.16	7.62	ns
		XCZU9	5.38	6.49	6.97	7.14	7.59	ns
		XCZU11	6.18	7.41	8.11	7.66	8.99	ns
		XCZU15	5.38	6.49	6.96	7.19	7.71	ns
		XCZU17	6.21	7.53	8.07	8.36	8.90	ns
		XCZU19	6.21	7.53	8.07	8.36	8.90	ns

Notes:

1. This table lists representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible I/O and CLB flip-flops are clocked by the global clock net.

Table 89: Global Clock Input to Output Delay With MMCM

Symbol	Description	Device	Speed Grade and V _{CCINT} Operating Voltages					Units
			0.90V	0.85V		0.72V		
			-3	-2	-1	-2	-1	
SSTL15 Global Clock Input to Output Delay using Output Flip-Flop, Fast Slew Rate, with MMCM.								
T _{ICKOFMMCMCC}	Global clock input and output flip-flop <i>with</i> MMCM.	XCZU2	N/A	2.22	2.43	2.96	2.94	ns
		XCZU3	N/A	2.22	2.43	2.96	2.94	ns
		XCZU4	2.47	2.47	2.78	3.04	3.35	ns
		XCZU5	2.47	2.47	2.78	3.04	3.35	ns
		XCZU6	2.15	2.15	2.36	2.86	2.86	ns
		XCZU7	2.32	2.32	2.57	3.06	3.13	ns
		XCZU9	2.15	2.15	2.36	2.86	2.86	ns
		XCZU11	2.64	2.64	2.96	3.25	3.55	ns
		XCZU15	2.18	2.18	2.38	2.88	2.90	ns
		XCZU17	2.44	2.44	2.66	3.19	3.17	ns
XCZU19	2.44	2.44	2.66	3.19	3.17	ns		

Notes:

1. This table lists representative values where one global clock input drives one vertical clock line in each accessible column, and where all accessible I/O and CLB flip-flops are clocked by the global clock net.
2. MMCM output jitter is already included in the timing calculation.

Table 92: Sampling Window

Description	Speed Grade and V _{CCINT} Operating Voltages					Units
	0.90V	0.85V		0.72V		
	-3	-2	-1	-2	-1	
T _{SAMP_BUFG} ⁽¹⁾	510	610	610	610	610	ps
T _{SAMP_NATIVE_DPA}	100	100	125	125	150	ps
T _{SAMP_NATIVE_BISC}	60	60	85	85	110	ps

Notes:

1. This parameter indicates the total sampling error of the Zynq UltraScale+ MPSoC DDR input registers, measured across voltage, temperature, and process. The characterization methodology uses the MMCM to capture the DDR input registers' edges of operation. These measurements include: CLK0 MMCM jitter, MMCM accuracy (phase offset), and MMCM phase shift resolution. These measurements do not include package or clock tree skew.

Table 102: GTH Transceiver User Clock Switching Characteristics⁽¹⁾ (Cont'd)

Symbol	Description	Data Width Conditions (Bit)		Speed Grade and V _{CCINT} Operating Voltages					Units
				0.90V	0.85V		0.72V		
		Internal Logic	Interconnect Logic	-3 ⁽²⁾	-2 ⁽²⁾⁽³⁾	-1 ⁽⁴⁾⁽⁵⁾	-2 ⁽³⁾	-1 ⁽⁵⁾	
F _{TXOUTPROGDIV}	TXOUTCLK maximum frequency sourced from TXPROGDIVCLK			511.719	511.719	511.719	511.719	511.719	MHz
F _{RXOUTPROGDIV}	RXOUTCLK maximum frequency sourced from RXPROGDIVCLK			511.719	511.719	511.719	511.719	511.719	MHz
F _{TXIN}	TXUSRCLK ⁽⁶⁾ maximum frequency	16	16, 32	511.719	511.719	390.625	390.625	322.266	MHz
		32	32, 64	511.719	511.719	390.625	390.625	322.266	MHz
		20	20, 40	409.375	409.375	312.500	312.500	257.813	MHz
		40	40, 80	409.375	409.375	312.500	312.500	257.813	MHz
F _{RXIN}	RXUSRCLK ⁽⁶⁾ maximum frequency	16	16, 32	511.719	511.719	390.625	390.625	322.266	MHz
		32	32, 64	511.719	511.719	390.625	390.625	322.266	MHz
		20	20, 40	409.375	409.375	312.500	312.500	257.813	MHz
		40	40, 80	409.375	409.375	312.500	312.500	257.813	MHz
F _{TXIN2}	TXUSRCLK2 ⁽⁶⁾ maximum frequency	16	16	511.719	511.719	390.625	390.625	322.266	MHz
		16	32	255.859	255.859	195.313	195.313	161.133	MHz
		32	32	511.719	511.719	390.625	390.625	322.266	MHz
		32	64	255.859	255.859	195.313	195.313	161.133	MHz
		20	20	409.375	409.375	312.500	312.500	257.813	MHz
		20	40	204.688	204.688	156.250	156.250	128.906	MHz
		40	40	409.375	409.375	312.500	312.500	257.813	MHz
		40	80	204.688	204.688	156.250	156.250	128.906	MHz
F _{RXIN2}	RXUSRCLK2 ⁽⁶⁾ maximum frequency	16	16	511.719	511.719	390.625	390.625	322.266	MHz
		16	32	255.859	255.859	195.313	195.313	161.133	MHz
		32	32	511.719	511.719	390.625	390.625	322.266	MHz
		32	64	255.859	255.859	195.313	195.313	161.133	MHz
		20	20	409.375	409.375	312.500	312.500	257.813	MHz
		20	40	204.688	204.688	156.250	156.250	128.906	MHz
		40	40	409.375	409.375	312.500	312.500	257.813	MHz
		40	80	204.688	204.688	156.250	156.250	128.906	MHz

Notes:

- Clocking must be implemented as described in *UltraScale Architecture GTH Transceiver User Guide* ([UG576](#)).
- For speed grades -3E, -2E, and -2I, a 16-bit and 20-bit internal data path can only be used for line rates less than 8.1875 Gb/s.
- For speed grade -2LE, a 16-bit and 20-bit internal data path can only be used for line rates less than 8.1875 Gb/s when V_{CCINT} = 0.85V or 6.25 Gb/s when V_{CCINT} = 0.72V.
- For speed grades -1E and -1I, a 16-bit and 20-bit internal data path can only be used for line rates less than 6.25 Gb/s.
- For speed grade -1LI, a 16-bit and 20-bit internal data path can only be used for line rates less than 6.25 Gb/s when V_{CCINT} = 0.85V or 5.15625 Gb/s when V_{CCINT} = 0.72V.
- When the gearbox is used, these maximums refer to the XCLK. For more information, see the *Valid Data Width Combinations for TX Asynchronous Gearbox* table in the *UltraScale Architecture GTH Transceiver User Guide* ([UG576](#)).

Table 114: GTY Transceiver User Clock Switching Characteristics⁽¹⁾ (Cont'd)

Symbol	Description	Data Width Conditions (Bit)		Speed Grade and V _{CCINT} Operating Voltages					Units
				0.90V	0.85V		0.72V		
		Internal Logic	Interconnect Logic	-3 ⁽²⁾	-2 ⁽²⁾⁽³⁾	-1 ⁽⁴⁾⁽⁵⁾	-2 ⁽³⁾	-1 ⁽⁵⁾	
F _{TXIN2}	TXUSRCLK2 ⁽⁶⁾ maximum frequency	16	16	511.719	511.719	390.625	390.625	322.266	MHz
		16	32	255.859	255.859	195.313	195.313	161.133	MHz
		32	32	511.719	511.719	390.625	390.625	322.266	MHz
		32	64	255.859	255.859	195.313	195.313	161.133	MHz
		64	64	511.719	440.781	402.832	402.832	195.313	MHz
		64	128	255.859	220.391	201.416	201.416	97.656	MHz
		20	20	409.375	409.375	312.500	312.500	257.813	MHz
		20	40	204.688	204.688	156.250	156.250	128.906	MHz
		40	40	409.375	409.375	312.500	350.000	257.813	MHz
		40	80	204.688	204.688	156.250	175.000	128.906	MHz
		80	80	409.375	352.625	322.266	352.625	156.250	MHz
		80	160	204.688	176.313	161.133	176.313	78.125	MHz
F _{RXIN2}	RXUSRCLK2 ⁽⁶⁾ maximum frequency	16	16	511.719	511.719	390.625	390.625	322.266	MHz
		16	32	255.859	255.859	195.313	195.313	161.133	MHz
		32	32	511.719	511.719	390.625	390.625	322.266	MHz
		32	64	255.859	255.859	195.313	195.313	161.133	MHz
		64	64	511.719	440.781	402.832	402.832	195.313	MHz
		64	128	255.859	220.391	201.416	201.416	97.656	MHz
		20	20	409.375	409.375	312.500	312.500	257.813	MHz
		20	40	204.688	204.688	156.250	156.250	128.906	MHz
		40	40	409.375	409.375	312.500	350.000	257.813	MHz
		40	80	204.688	204.688	156.250	175.000	128.906	MHz
		80	80	409.375	352.625	322.266	352.625	156.250	MHz
		80	160	204.688	176.313	161.133	176.313	78.125	MHz

Notes:

- Clocking must be implemented as described in the *UltraScale Architecture GTY Transceiver User Guide* ([UG578](#)).
- For speed grades -3E, -2E, and -2I, a 16-bit and 20-bit internal data path can only be used for line rates less than 8.1875 Gb/s.
- For speed grade -2LE, a 16-bit and 20-bit internal data path can only be used for line rates less than 8.1875 Gb/s when V_{CCINT} = 0.85V or 6.25 Gb/s when V_{CCINT} = 0.72V.
- For speed grades -1E and -1I, a 16-bit and 20-bit internal data path can only be used for line rates less than 6.25 Gb/s.
- For speed grade -1LI, a 16-bit and 20-bit internal data path can only be used for line rates less than 6.25 Gb/s when V_{CCINT} = 0.85V or 5.15625 Gb/s when V_{CCINT} = 0.72V.
- When the gearbox is used, these maximums refer to the XCLK. For more information, see the *Valid Data Width Combinations for TX Asynchronous Gearbox* table in the *UltraScale Architecture GTY Transceiver User Guide* ([UG578](#)).

Integrated Interface Block for 100G Ethernet MAC and PCS

More information and documentation on solutions using the integrated 100 Gb/s Ethernet block can be found at [UltraScale+ Integrated 100G Ethernet MAC/PCS](#). The *UltraScale Architecture and Product Overview (DS890)* lists how many blocks are in each Zynq UltraScale+ MPSoC.

Table 121: Maximum Performance for 100G Ethernet Designs

Symbol	Description	Speed Grade and V _{CCINT} Operating Voltages					Units
		0.90V	0.85V		0.72V		
		-3	-2 ⁽¹⁾	-1	-2	-1 ⁽²⁾	
F _{TX_CLK}	Transmit clock	390.625	390.625	322.223	322.223	322.223	MHz
F _{RX_CLK}	Receive clock	390.625	390.625	322.223	322.223	322.223	MHz
F _{RX_SERDES_CLK}	Receive serializer/deserializer clock	390.625	390.625	322.223	322.223	322.223	MHz
F _{DRP_CLK}	Dynamic reconfiguration port clock	250.00	250.00	250.00	250.00	250.00	MHz

Notes:

1. The maximum clock frequency of 390.625 MHz only applies to the CAUI-10 interface. The maximum clock frequency for the CAUI-4 interface is 322.223 MHz.
2. The CAUI-4 interface is not supported by -1L speed grade devices where V_{CCINT}=0.72V.

Integrated Interface Block for PCI Express Designs

More information and documentation on solutions for PCI Express designs can be found at [PCI Express](#). The *UltraScale Architecture and Product Overview (DS890)* lists the Zynq UltraScale+ MPSoCs that include this block.

Table 122: Maximum Performance for PCI Express Designs⁽¹⁾⁽²⁾

Symbol	Description	Speed Grade and V _{CCINT} Operating Voltages					Units
		0.90V	0.85V		0.72V		
		-3	-2	-1	-2	-1	
F _{PIPECLK}	Pipe clock maximum frequency.	250.00	250.00	250.00	250.00	250.00	MHz
F _{CORECLK}	Core clock maximum frequency.	500.00	500.00	500.00	250.00	250.00	MHz
F _{DRPCLK}	DRP clock maximum frequency.	250.00	250.00	250.00	250.00	250.00	MHz
F _{MCAPCLK}	MCAP clock maximum frequency.	125.00	125.00	125.00	125.00	125.00	MHz

Notes:

1. PCI Express Gen4 operation is supported for x1, x2, x4, and x8 widths.
2. PCI Express Gen4 operation is supported in -3E, -2E, and -2I speed grades.

Date	Version	Description of Revisions
02/10/2017	1.2	Updated some of the maximum voltages in the Processor System (PS) section and other specifications in the Programmable Logic (PL) and GTH or GTY Transceiver sections of Table 1 . Updated Table 2 , Table 4 , Table 6 , Table 7 , and Table 9 . Revised the Power Supply Sequencing section including Table 10 . Added PS and VCU ramp times to Table 11 . Revised V_{ODIFF} in Table 24 . Updated Table 25 . Added Note 1 to Table 26 . Table 30 replaces the previous three PS memory performance tables. Added values to Table 34 , Table 37 , and Table 38 . Deleted the waveforms in the PS Switching Characteristics section (Figures 1-16 and Figures 25-26). Revised values in the PS NAND Memory Controller Interface section. Added and updated data in Table 40 . Added Note 3 to Table 41 . Added Note 3 to Table 42 . Added Note 1 to Table 45 . Updated Table 48 and removed Note 3 . Added data to Table 56 . Updated Table 60 . Added Table 61 . Updated Table 63 . Revised Table 69 . Added data to Table 70 . Added Note 2 to Table 71 . Updated Table 74 and added Note 4 . Updated V_L and V_H values in Table 78 . Added T_{MINPER_CLK} , revised F_{REFCLK} , and Note 1 to Table 82 . Added $MMCM_F_{DPRCLK_MAX}$ to Table 85 and $PLL_F_{DPRCLK_MAX}$ to Table 86 . Added data to Table 94 , Table 96 , Table 98 , Table 101 , and updated the note references in Table 102 . Updated Table 103 and added Note 8 . Updated Table 104 and added Note 7 . Added more protocols, Note 1 and Note 2 to Table 105 . Removed the GTH Transceiver Protocol Jitter Characteristics section because it is covered in Table 105 . Added Note 1 to Table 109 . Added data to Table 106 , Table 108 , Table 110 , Table 113 . Added Note 2 to Table 112 . Added note references in Table 114 . Updated Table 115 and added Note 8 . Updated Table 116 and added Note 7 . Added more protocols and Note 3 to Table 117 . Removed the GTy Transceiver Protocol Jitter Characteristics section because it is covered in Table 117 . Revised Table 124 . Added T_{POR} and updated F_{ICAPCK} in Table 127 . Updated the Automotive Applications Disclaimer .
06/20/2016	1.1	Updated the Summary description. In Table 1 , revised V_{IN} for HP I/O banks and added clarifications to some descriptions and symbols. Added I_{RPU} , I_{RPD} , and Note 4 to Table 2 and updated $V_{PS_MGTRAVCC}$, the PL System Monitor section, and Note 3 and Note 5 . Updated Note 5 in Table 4 . Updated the PS Power-On/Off Power Supply Sequencing section including all the voltage supply names. Added $MIPI_DPHY_DCI$ to Table 14 , Table 15 , and Table 17 . Updated Table 23 , including removing the V_{CCO} specification and adding Note 1 . Added Note 1 to Table 24 . Updated Table 25 speed specifications for Vivado Design Suite 2016.1. Added values to Table 28 . Updated the -2 value in Table 29 . Added $F_{DPLIVEVIDEO}$ and updated $F_{FCIDMACLK}$ in Table 33 . Added VCO frequencies to Table 36 . Added the T_{PSPOR} minimum to Table 37 and updated Note 1 . Added Table 38 . Added value delineation over V_{CCINT} operating voltages in Table 39 . Revised values for F_{TCK} and T_{TAPTCK}/T_{TCKTAP} in Table 40 and added value delineation over V_{CCINT} operating voltages. Updated the PS NAND Memory Controller Interface section. Revised some units and Note 1 in Table 41 and Table 42 . Removed Figure 6: Quad-SPI Interface (Feedback Clock Disabled) Timing. Updated Note 1 of Table 43 . Added $F_{TSI_REF_CLK}$ to Table 44 and updated Note 1 . In Table 45 , revised $T_{DCSDHCLK1}$, $T_{DCSDHCLK2}$, and $T_{DCSDHCLK3}$ and Note 1 . In Table 46 , revised Note 1 . In Table 47 , revised Note 1 . Revised Table 48 , including Note 1 , and added Note 2 and Note 3 . In Table 49 , Table 50 , Table 51 , and Table 53 , revised Note 1 . Updated Table 71 . Replaced Table 74 . Updated Table 75 and Table 76 . Updated Table 78 and Table 79 . In Table 80 , added the Block RAM and FIFO Clock-to-Out Delays section. Updated the R_{IN} and C_{EXT} values in Table 57 and Table 95 . Updated the -2 (0.72V) and -1 (0.72V) values and added Note 1 to Table 97 . Added Table 100 and Table 112 . Added Note 2 to Table 106 . Revised data in Table 109 . Revised Table 114 . Revised data and added notes in the Integrated Interface Block for Interlaken section and Table 121 . Moved Table 123 . Revised INL in Table 124 . Added notes to Table 125 and Table 126 . In the eFUSE and Programming Conditions table, updated the I_{PSFS} description.
11/24/2015	1.0	Initial Xilinx release.